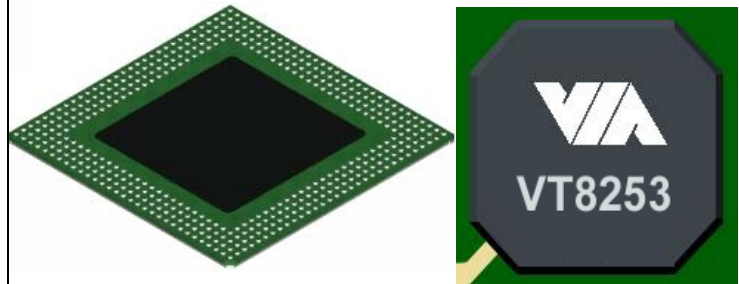


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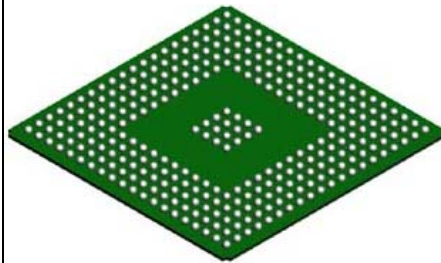
## Component      Package

BGA(Ball Grid Array)  
焊球阵列

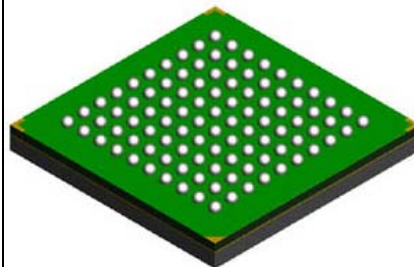


EBGA

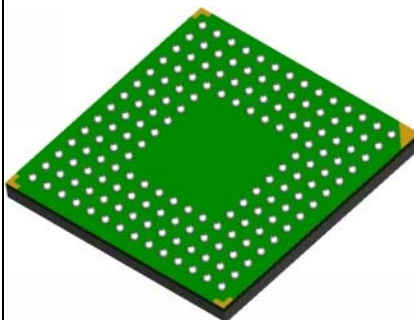
PBGA  
(Plastic Ball Grid Array)



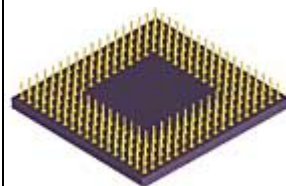
FBGA  
(Flex BGA)

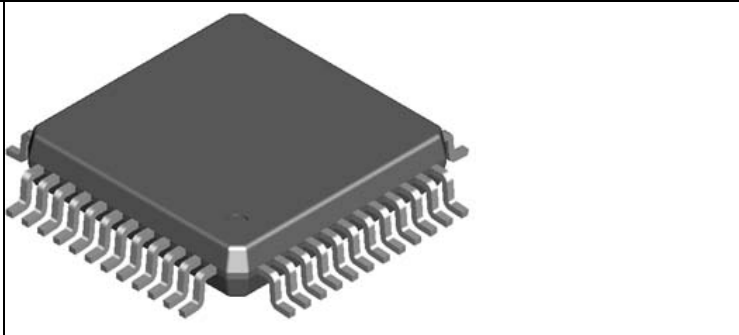
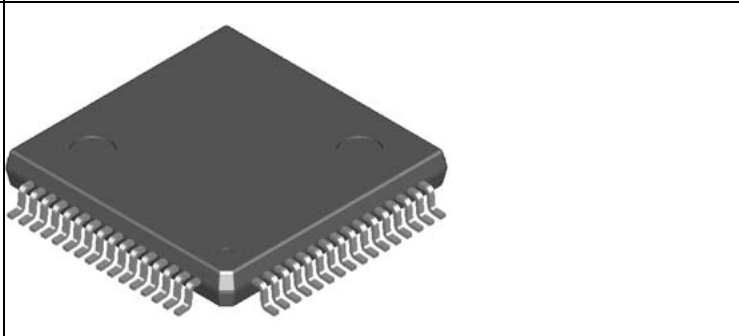
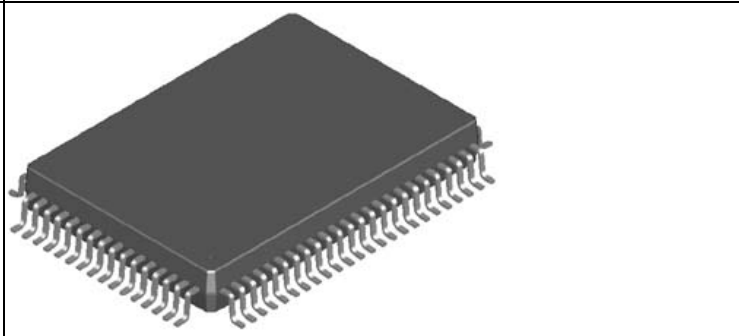
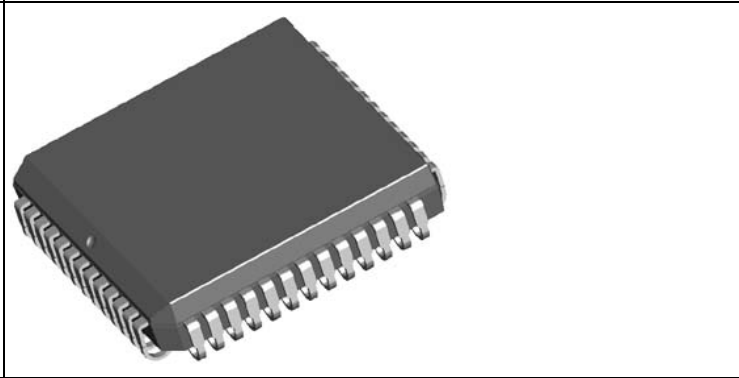
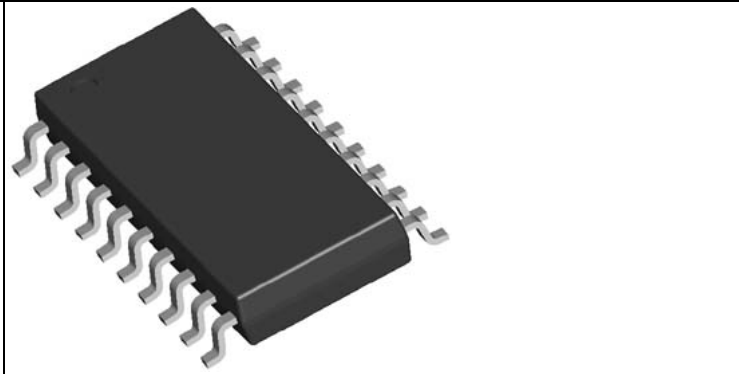


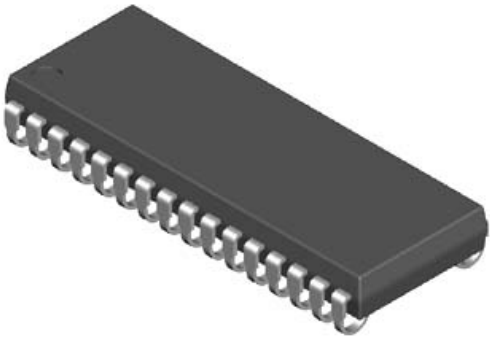
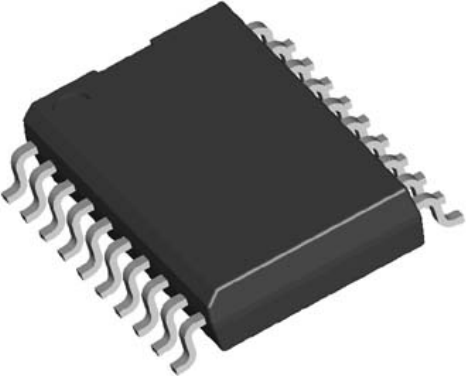
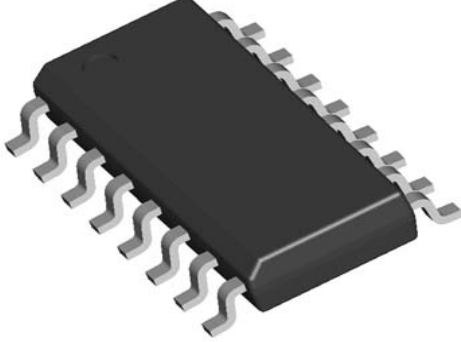
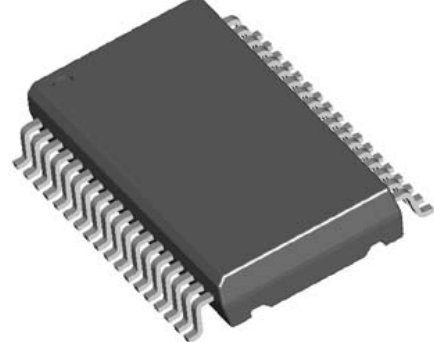
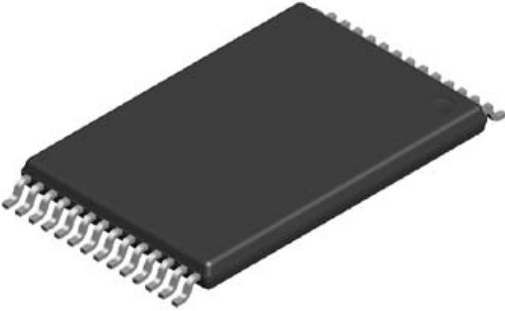
LBGA

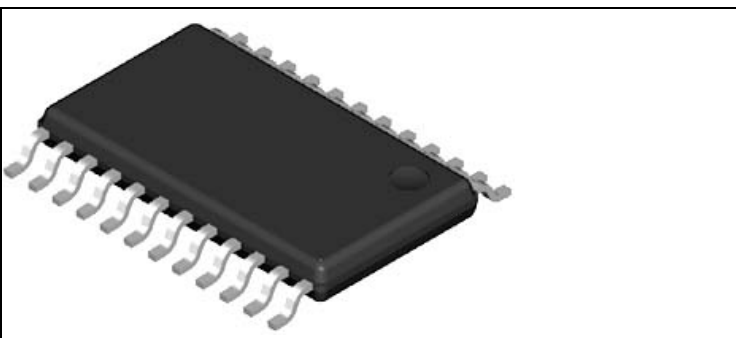
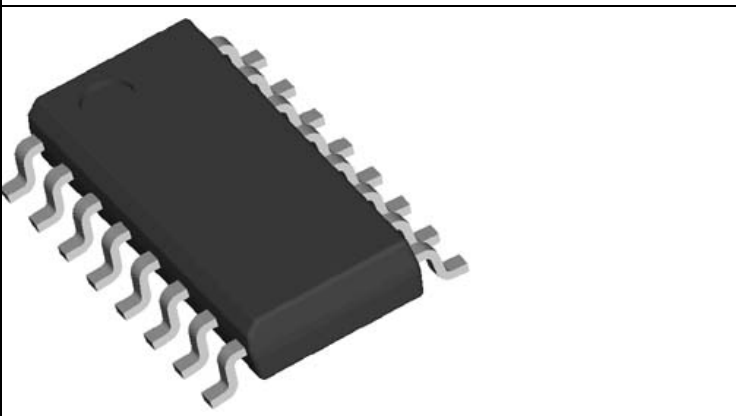
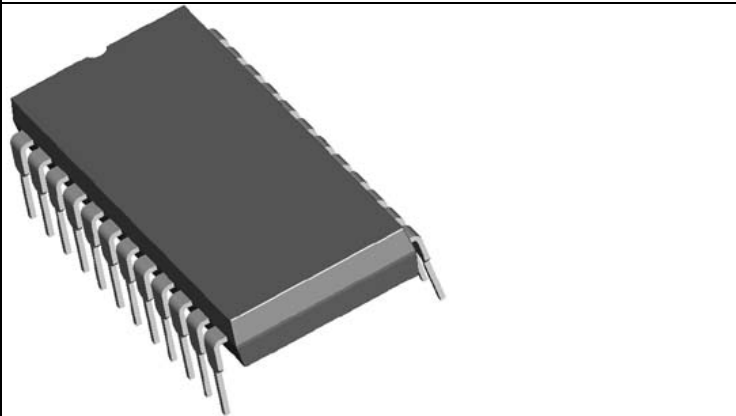
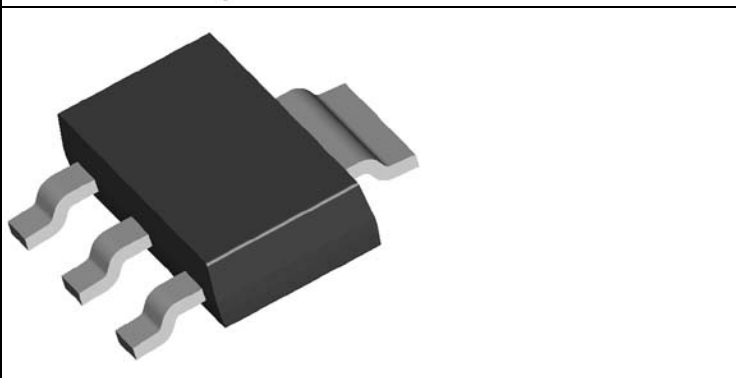


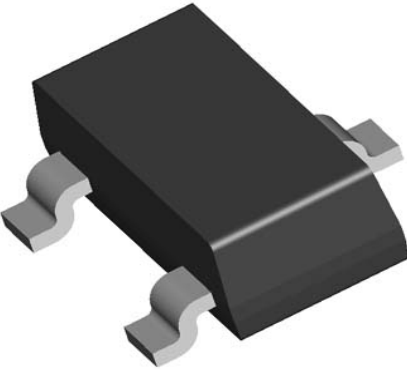

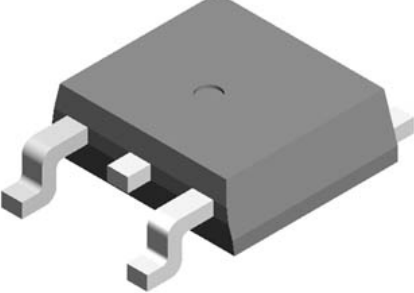
CPGA  
(Ceramic Pin Grid Array)



<p>LQFP(Quad Flat Package) L 形四边引线封装 扁平封装</p>	
<p>TQFP (Thin Quad Flat Package) 薄型 QFP</p>	
<p>PQFP (Plastic Quad Flat Package) 塑封 QFP</p>	
<p>PLCC (Plastic Leaded Chip Carrier) 塑料丁形四边引线片式载体</p>	
<p>SOP(Small Outline Package) 翼形 (L 形) 引线小外形封装</p>	

<p>SOJ</p> <p>J 型引脚小外形封装</p>	 A black, rectangular surface-mount package with a single row of J-shaped pins along one long edge.
<p>SOIC WIDE</p> <p>(Small Outline Integrate Carrier)</p> <p>宽体小外形集成电路</p>	 A black, rectangular surface-mount package with two rows of gull-wing pins along the long edges.
<p>SOIC NARROW</p> <p>窄体小外形集成电路</p>	 A black, rectangular surface-mount package with two rows of gull-wing pins along the long edges, appearing narrower than the SOIC WIDE package.
<p>SSOP</p> <p>(Shrink Small Outline Package)</p> <p>缩小型 SOP</p>	 A black, rectangular surface-mount package with two rows of gull-wing pins along the long edges, appearing narrower than the SOIC NARROW package.
<p>TSOP1</p> <p>(Thin Small Outline Package)</p> <p>薄小外形封装</p>	 A black, rectangular surface-mount package with two rows of gull-wing pins along the long edges, appearing the narrowest of the packages shown.

<p>TSSOP (Thin Shrink Small Outline Package) 薄的缩小型 SOP</p>	 A 3D perspective view of a TSSOP package, showing a black rectangular chip with a thin profile and two rows of gull-wing shaped leads.
<p>PSOP (Plastic Small Outline Package) 塑封 SOP</p>	 A 3D perspective view of a PSOP package, showing a black rectangular chip with a slightly thicker profile than TSSOP and two rows of gull-wing shaped leads.
<p>QSOP (Quarter Size Outline Package)</p>	
<p>SOW</p>	
<p>DIP (Dual In-Line Package) 双列直插封装</p>	 A 3D perspective view of a DIP package, showing a black rectangular chip with a thick profile and two rows of long, straight leads.
<p>SOT223</p>	 A 3D perspective view of a SOT223 package, showing a small black chip with a gull-wing shaped lead on one side and three leads on the other.

SOT23	
TO220(5P)	
TO252	
TO263	Same as above

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